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Attorney Docket No: 42390P10075

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Pon, Harry

Application No.: 09/822,944

Filed: 03/30/2001

For: INSULATED BOND WIRE ASSEMBLY
PROCESS TECHNOLOGY FOR
INTEGRATED CIRCUITS

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Examiner: Unknown

Art Unit: 2811

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Applicant requests the Examiner to enter the following Preliminary Amendment. A clean version of the amended paragraphs and claims is shown below. A marked-up version is shown in Appendix A.

IN THE SPECIFICATIONS:

Please amend the following paragraphs as indicated.

[0009] Fig. 3 shows an embodiment of the invention having two integrated circuits connected to each other and to an underlying substrate through multiple insulated bond wires.